

Technical Note

TN_166

FTDI Example IC PCB Footprints

Version 1.1

Issue Date: 2017-05-16

This Technical Note shows examples of FTDI IC PCB footprints which can be used as a guide for creating your own IC PCB footprints.

Use of FTDI devices in life support and/or safety applications is entirely at the user's risk, and the user agrees to defend, indemnify and hold FTDI harmless from any and all damages, claims, suits or expense resulting from such use.

Unit 1, 2 Seaward Place, Glasgow G41 1HH, United Kingdom Tel.: +44 (0) 141 429 2777 Fax: + 44 (0) 141 429 2758

Web Site: http://ftdichip.com



Table of Contents

1	In	troduction	. 6
	1.1	Scope	6
	1.1	.1 Unavailable Footprints	6
2	ΑI	Scaled Footprints	. 7
	2.1	DFN Packages	7
	2.2	QFP Packages	7
	2.3	QFN Packages	7
	2.4	SSOP Packages	7
3	Pa	ckages by Product	. 8
	3.1	DFN Packages	8
	3.2	QFP Packages	8
		QFN Packages	
	3.4	SSOP Packages	9
4	10)-pin DFN:	10
		Scaled Footprint	
		Annotated Footprint	
		e-pin DFN:	
	5.1	Scaled Footprint	11
		Annotated Footprint	
		5-pin QFN (3mm x 3mm):	
		Scaled Footprint	
		Annotated Footprint	
		5-pin QFN (4mm x 4mm):	
		Scaled Footprint	
		Annotated Footprint	
		5-pin SSOP	
		Scaled Footprint	
	0.I	Scaled FOOtprint	14





8	2	Annotated Footprint	14
		pin TSSOP	
		Scaled Footprint	
		Annotated Footprint	
10	20)-pin QFN	16
10	0.1	Scaled Footprint	.16
10	0.2	Annotated Footprint	.16
11	20)-pin SSOP	17
1:	1.1	Scaled Footprint	.17
1:	1.2	Annotated Footprint	.17
12	24	I-pin QFN	18
12	2.1	Scaled Footprint	.18
12	2.2	Annotated Footprint	.18
13	24	1-pin SSOP	19
13	3.1	Scaled Footprint	.19
13	3.2	Annotated Footprint	.19
14	28	B-pin QFN	20
		Scaled Footprint	
		Annotated Footprint	
		B-pin SSOP	
		Scaled Footprint	
		Annotated Footprint	
		B-pin TSSOP	
		•	
		Scaled Footprint	
		Annotated Footprint	
		B-pin WQFN	
17	7.1	Scaled Footprint	.23
17	7.2	Annotated Footprint	.23







18	32	2-pin LQFP	24
18	3.1	Scaled Footprint	24
18	3.2	Annotated Footprint	24
19	32	2-pin VQFN/QFN (5mm x 5mm)	25
19	9.1	Scaled Footprint	25
19	9.2	Annotated Footprint	.25
20	32	2-pin QFN (7mm x 7mm)	26
20).1	Scaled Footprint	.26
20).2	Annotated Footprint	26
21	48	8-pin LQFP	27
21	l. 1	Scaled Footprint	.27
21	L .2	Annotated Footprint	.27
22	48	B-pin VQFN/WQFN (7mm x 7mm)	28
22	2.1	Scaled Footprint	.28
22	2.2	Annotated Footprint	28
23	48	B-pin QFN (8mm x 8mm)	29
23	3.1	Scaled Footprint	.29
23	3.2	Annotated Footprint	29
24	56	5-pin QFN (7mm x 7mm)	30
24	l.1	Scaled Footprint	.30
24	l.2	Annotated Footprint	.30
25	56	5-pin VQFN (8mm x 8mm)	31
25	5.1	Scaled Footprint	31
25	5.2	Annotated Footprint	31
26	64	l-pin LQFP	32
26	5.1	Scaled Footprint	.32
26	5.2	Annotated Footprint	.32
27	64	l-pin TQFP	33
		-	





FTDI
Chip

27	.1	Scaled Footprint	.33	
27	2	Annotated Footprint	33	
28	64	-pin QFN (8mm x 8mm)	34	
28	3.1	Scaled Footprint	34	
28	3.2	Annotated Footprint	34	
29	64	-pin QFN (9mm x 9mm)	35	
29	.1	Scaled Footprint	35	
29	.2	Annotated Footprint	35	
2	9.2.1	Additional Information	. 36	
30	76	-pin QFN	37	
30	.1	Scaled Footprint	37	
30	.2	Annotated Footprint	37	
31	80	-pin LQFP	38	
31	.1	Scaled Footprint	38	
31	.2	Annotated Footprint	38	
32	10	0-pin LQFP	39	
32	.1	Scaled Footprint	39	
32	.2	Annotated Footprint	39	
33	10	0-pin QFN	40	
33	.1	Scaled Footprint	40	
33	.2	Annotated Footprint	40	
34	Co	ntact Information	41	
Apr	en	dix A – References	42	
		nent References		
	Acronyms and Abbreviations42			
		dix B – List of Tables & Figures		
	List of Tables43			
	List of Figures43			



Technical Note **TN_166 FTDI Example IC PCB Footprints**

Version 1.1

Document Reference No.: FT_001321 Clearance No.: FTDI# 501

Appendix C – Revision History	45
-------------------------------	----

1 Introduction

This Technical Note shows examples of FTDI IC PCB footprints which can be used as a guide for creating your own PCB footprints.

The IC footprints in this document are sourced from various FTDI hardware such as development and application <u>modules</u> and demo hardware, using the most common and cost effective package types.

Most FTDI IC footprints are included in this document; however some are missing when a package type has not been used for specific FTDI hardware. See Table 1.1 for unavailable footprints.

The IC footprints in this document provide:

- A 1:1 scaled IC footprint
- An annotated IC footprint showing some key measurements

All dimensions shown are in millimeters (mm).

Additionally, a range of USB Interface IC solutions from FTDI Chip available through AltiumLive.

To view Altium files, you need either the full version of 'Altium Designer', or 'Altium Viewer' which can be downloaded for free from Altium's web site.

http://www.ftdichip.com/Support/Documents/PCBData.htm

Note that all IC footprints may not be available through AltiumLive. It is a live dBase continually being updated.

1.1 Scope

These IC PCB footprints can be used as a guide to create your own IC PCB footprints with particular PCB design tools other than Altium.

Please refer to the IC datasheet for full IC package parameters.

Note: No guarantees can be provided in this document. These can be used as a guide only.

Note: FTDI <u>Cables</u> and <u>Modules</u> are recommended for product test and development prior to custom hardware development.

1.1.1 Unavailable Footprints

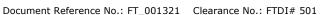
Table 1.1 shows that there are some footprints not included in this document as, for example, they have never been used for specific hardware developments within FTDI. Other package options for those products exist and are included in this document.

Note: This is correct at the time of writing and newer products may not be included.

Package	Part Numbers
32-pin WQFN	FT51BQ
44-pin LQFP	FT51AL

Table 1.1 Unavailable Footprints







2 All Scaled Footprints

This section shows all packages scaled to 1:1 size to show the exact package size which can help when selecting a package to use in your design.

Note that not all packages are available for all products. See Section 3 'Packages by Product' in this document, the product datasheet, or check the IC webpage:

http://www.ftdichip.com/Products/ICs.htm

2.1 DFN Packages

Figure 2.1 shown in pin count order from left to right: DFN-10, DFN-12.



Figure 2.1 DFN Packages

2.2 QFP Packages

Figure 2.2 shown in pin count order from left to right:

LQFP-32, LQFP-48, LQFP-64, TQFP-64, LQFP-80, LQFP-100.

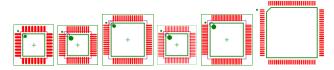


Figure 2.2 QFP Packages

2.3 QFN Packages

Figure 2.3 shown in pin count order from left to right:

QFN-16 (3x3), QFN-16 (4x4), QFN-20, QFN-24, QFN-28, WQFN-28, QFN-32 (5x5), QFN-32 (7x7), QFN-48 (7x7), QFN-48 (8x8), QFN-56 (7x7), VQFN-56 (8x8), QFN-64 (8x8), QFN-64 (9x9), QFN-76, QFN-100.

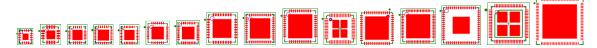


Figure 2.3 QFN Packages

2.4 SSOP Packages

Figure 2.4 shown in pin count order from left to right:

SSOP-16, TSSOP-16, SSOP-20, SSOP-24, SSOP-28, TSSOP-28.

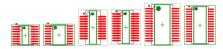


Figure 2.4 SSOP Packages

3 Packages by Product

Package availability for FTDI products is shown in this section.

3.1 DFN Packages

Package	Part Numbers
DFN-10	FT200XD
DFN-12	FT234XD

Table 3.1 DFN Packages

3.2 QFP Packages

Package	Part Numbers
LQFP-32	FT232BL, FT245BL, FT311D-32L1C, FT312D-32L1C, VNC2-32L1B
LQFP-48	FT232HL, FT2232D, VNC1L-1A, VNC2 48L1B
LQFP-64	FT2232HL, FT4232HL, FT313HL, VNC2- 64L1B
<u>TQFP-64</u>	FT313HP
<u>LQFP-80</u>	FT905L, FT906L, FT907L, FT908L
LQFP-100	FT900L, FT901L, FT902L, FT903L

Table 3.2 QFP Packages

3.3 QFN Packages

Package	Part Numbers
QFN-16 (3x3)	FT121Q
QFN-16 (4x4)	FT201XQ, FT220XQ, FT230XQ
<u>QFN-20</u>	FT221XQ, FT231XQ
QFN-24	FT240XQ
<u>QFN-28</u>	FT120Q, FT122Q
WQFN-28	FT260Q
QFN-32 (5x5)	FT232RQ, FT245RQ, FT4222HQ
QFN-32 (7x7)	FT311D-32Q1C, FT312D-32Q1C, VNC2-32Q1B
QFN-48 (7x7)	FT51AQ, FT800Q, FT801Q, FT810Q, FT811Q
QFN-48 (8x8)	FT232HQ, VNC2-48Q1B
QFN-56 (7x7)	FT600Q
<u>VQFN-56 (8x8)</u>	FT2232H-56Q, FT4232H-56Q, FT812Q, FT813Q

Package	Part Numbers
QFN-64 (8x8)	VNC2-64Q1B
QFN-64 (9x9)	FT2232HQ, FT4232HQ, FT313HQ
<u>QFN-76</u>	FT601Q, FT905Q, FT906Q, FT907Q, FT908Q
QFN-100	FT900Q, FT901Q, FT902Q, FT903Q

Table 3.3 QFN Packages

3.4 SSOP Packages

Package	Part Numbers
SSOP-16	FT201XS, FT220XS, FT230XS
TSSOP-16	FT121T
SSOP-20	FT221XS, FT231XS
SSOP-24	FT240XS
SSOP-28	FT232RL, FT245RL, FT51CS
TSSOP-28	FT120T, FT122T, FT260S

Table 3.4 SSOP Packages

10-pin DFN 4

The 10-pin DFN is used on the following product:

FT200XD

This package is nominally 3.00mm x 3.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

4.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 4.1 10-pin DFN Scaled Footprint

4.2 Annotated Footprint

The annotated footprint shows key measurements.

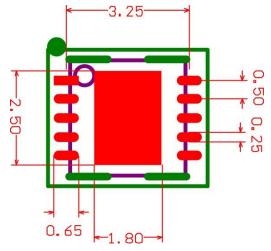


Figure 4.2 10-pin DFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

5 12-pin DFN

The 12-pin DFN is used on the following product:

FT234XD

This package is nominally 3.00mm x 3.00mm. The solder pads are on a 0.45mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

5.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 5.1 12-pin DFN Scaled Footprint

5.2 Annotated Footprint

The annotated footprint shows key measurements.

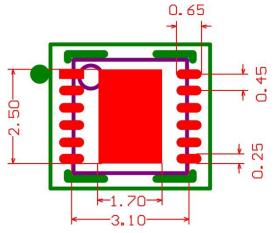


Figure 5.2 12-pin DFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

6 16-pin QFN (3mm x 3mm)

The 16-pin QFN (3mm x 3mm) is used on the following product:

• <u>FT1210</u>

This package is nominally 3.00mm x 3.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

6.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 6.1 16-pin QFN (3mm x 3mm) Scaled Footprint

6.2 Annotated Footprint

The annotated footprint shows key measurements.

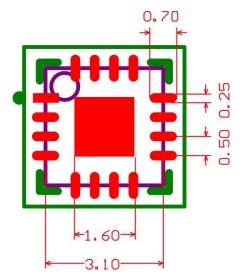


Figure 6.2 16-pin QFN (3mm x 3mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.



7 16-pin QFN (4mm x 4mm)

The 16-pin QFN (4mm x 4mm) is used on the following products:

- FT201XO
- FT220XQ
- FT230XC

This package is nominally 4.00mm x 4.00mm. The solder pads are on a 0.65mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

7.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 7.1 16-pin QFN (4mm x 4mm) Scaled Footprint

7.2 Annotated Footprint

The annotated footprint shows key measurements.

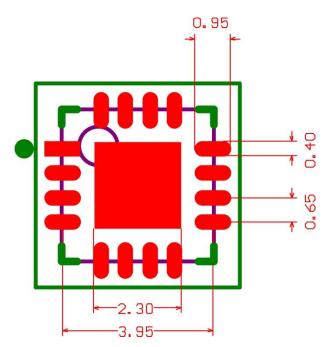


Figure 7.2 16-pin QFN (4mm x 4mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.



8 16-pin SSOP-

The 16-pin SSOP is used on the following products:

- FT201XS
- FT220XS
- FT230X9

This package is nominally $4.90 \, \text{mm} \times 3.91 \, \text{mm}$ body $(4.90 \, \text{mm} \times 5.99 \, \text{mm}$ including pins). The solder pads are on a $0.635 \, \text{mm}$ pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

8.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 8.1 16-pin SSOP Scaled Footprint

8.2 Annotated Footprint

The annotated footprint shows key measurements.

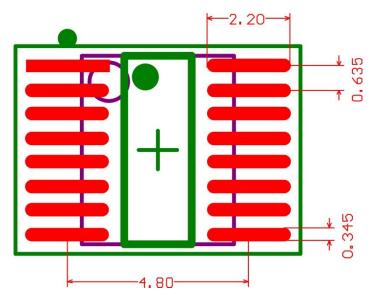


Figure 8.2 16-pin SSOP Annotated Footprint

9 16-pin TSSOP

The 16-pin TSSOP is used on the following product:

FT121T

This package is nominally 5.0mm \times 4.4mm body (5.0mm \times 6.4mm including pins). The solder pads are on a 0.65mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

9.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 9.1 16-pin TSSOP Scaled Footprint

9.2 Annotated Footprint

The annotated footprint shows key measurements.

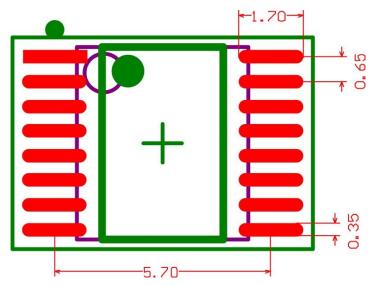


Figure 9.2 16-pin TSSOP Annotated Footprint





20-pin QFN 10

The 20-pin QFN is used on the following products:

- FT221XQ
- FT231XQ

This package is nominally 4.00mm x 4.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

10.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 10.1 20-pin QFN Scaled Footprint

10.2 Annotated Footprint

The annotated footprint shows key measurements.

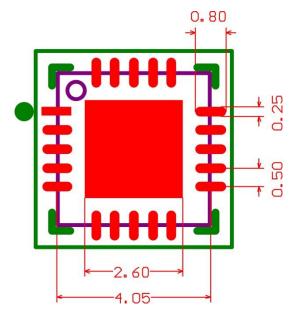


Figure 10.2 20-pin QFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.



11 20-pin SSOP

The 20-pin SSOP is used on the following products:

- FT221XS
- FT231XS

This package is nominally $8.66 \, \text{mm} \times 3.91 \, \text{mm}$ body ($8.66 \, \text{mm} \times 5.99 \, \text{mm}$ including pins). The solder pads are on a $0.635 \, \text{mm}$ pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

11.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 11.1 20-pin SSOP Scaled Footprint

11.2 Annotated Footprint

The annotated footprint shows key measurements.

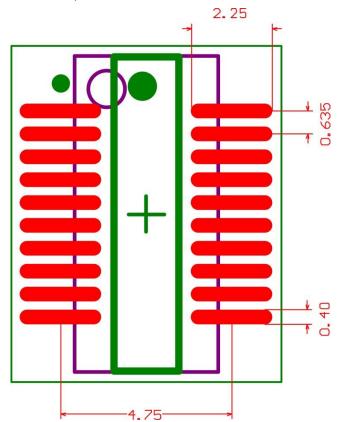


Figure 11.2 20-pin SSOP Annotated Footprint





12 24-pin QFN

The 24-pin QFN is used on the following product:

FT240XQ

This package is nominally 4.00mm x 4.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

12.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 12.1 24-pin QFN Scaled Footprint

12.2 Annotated Footprint

The annotated footprint shows key measurements.

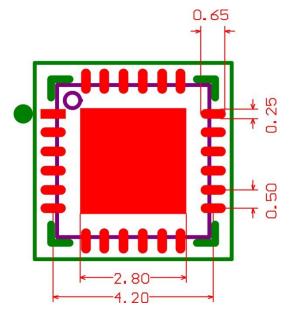


Figure 12.2 24-pin QFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

13 24-pin SSOP

The 24-pin SSOP is used on the following products:

FT240XS

This package is nominally $8.66 \, \text{mm} \times 3.91 \, \text{mm}$ body ($8.66 \, \text{mm} \times 5.99 \, \text{mm}$ including pins). The solder pads are on a $0.635 \, \text{mm}$ pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

13.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 13.1 24-pin SSOP Scaled Footprint

13.2 Annotated Footprint

The annotated footprint shows key measurements.

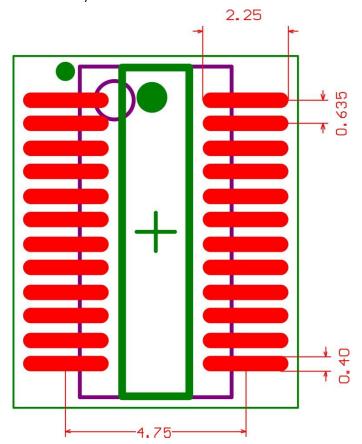


Figure 13.2 24-pin SSOP Annotated Footprint

14 28-pin QFN

The 28-pin QFN is used on the following products:

- FT120Q
- FT122Q

This package is nominally 4.00mm x 4.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

14.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 14.1 28-pin QFN Scaled Footprint

14.2 Annotated Footprint

The annotated footprint shows key measurements.

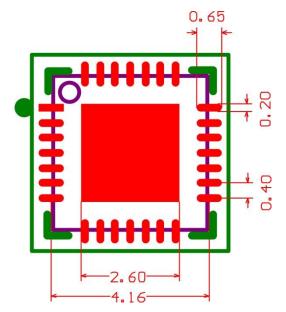


Figure 14.2 28-pin QFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

28-pin SSOP **15**

The 28-pin SSOP is used on the following products:

- FT245RL

This package is nominally $5.30 \, \text{mm} \times 10.20 \, \text{mm}$ body ($7.80 \, \text{mm} \times 10.20 \, \text{mm}$ including pins). The solder pads are on a 0.65mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

15.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 15.1 28-pin SSOP Scaled Footprint

15.2 Annotated Footprint

The annotated footprint shows key measurements.

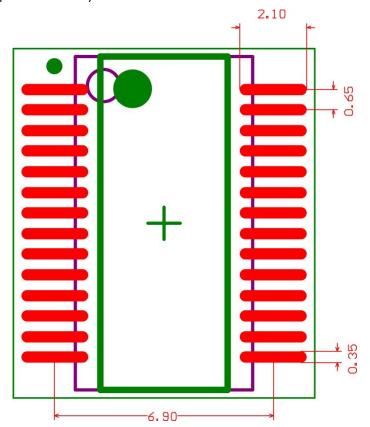


Figure 15.2 28-pin SSOP Annotated Footprint

TN_166 FTDI Example IC PCB Footprints

Document Reference No.: FT_001321 Clearance No.: FTDI# 501

16 28-pin TSSOP

The 28-pin TSSOP is used on the following products:

- FT120T
- FT122
- FT260S

This package is nominally $9.7mm \times 4.4mm$ body $(9.7mm \times 6.4mm$ including pins). The solder pads are on a 0.65mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

16.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 16.1 28-pin TSSOP Scaled Footprint

16.2 Annotated Footprint

The annotated footprint shows key measurements.

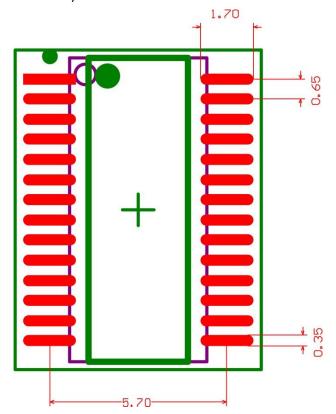


Figure 16.2 28-pin TSSOP Annotated Footprint

17 28-pin WQFN

The 28-pin WQFN is used on the following product:

FT260Q

This package is nominally 5.00mm x 5.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

17.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 17.1 28-pin WQFN Scaled Footprint

17.2 Annotated Footprint

The annotated footprint shows key measurements.

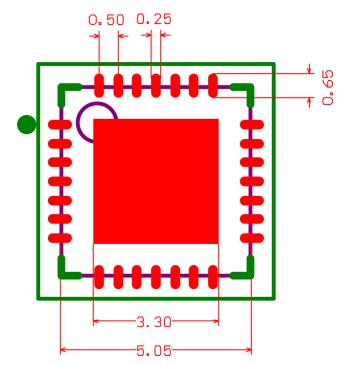


Figure 17.2 28-pin WQFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

18 32-pin LQFP

The 32-pin LQFP is used on the following products:

- VNC2-32L1B
- FT311D-32L1C
- FT312D-32L1C
- FT232BL
- FT245BL

This package is nominally 9.00mm x 9.00mm. The solder pads are on a 0.80mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

18.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 18.1 32-pin LQFP Scaled Footprint

18.2 Annotated Footprint

The annotated footprint shows key measurements.

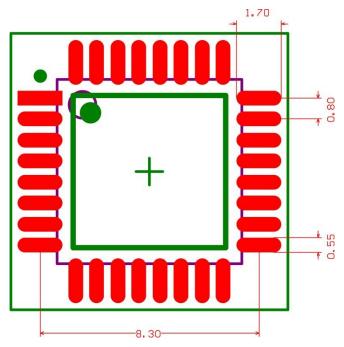
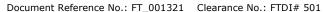


Figure 18.2 32-pin LQFP Annotated Footprint







19 32-pin VQFN/QFN (5mm x 5mm)

The 32-pin VQFN/QFN (5mm x 5mm) is used on the following products:

- FT232RO
- FT245RQ
- FT4222HQ

This package is nominally 5.00mm x 5.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

19.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 19.1 32-pin VQFN/QFN (5mm x 5mm) Scaled Footprint

19.2 Annotated Footprint

The annotated footprint shows key measurements.

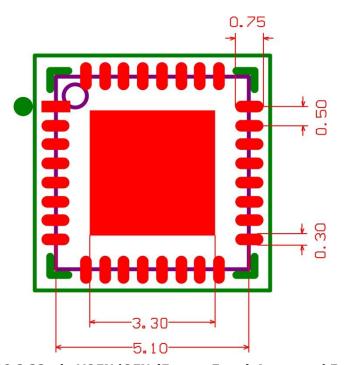


Figure 19.2 32-pin VQFN/QFN (5mm x 5mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

20 32-pin QFN (7mm x 7mm)

The 32-pin QFN (7mm x 7mm) is used on the following products:

- VNC2-32Q1B
- FT311D-32Q1C
- FT312D-32Q1C

This package is nominally 7.00mm x 7.00mm. The solder pads are on a 0.65mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

20.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 20.1 32-pin QFN (7mm x 7mm) Scaled Footprint

20.2 Annotated Footprint

The annotated footprint shows key measurements.

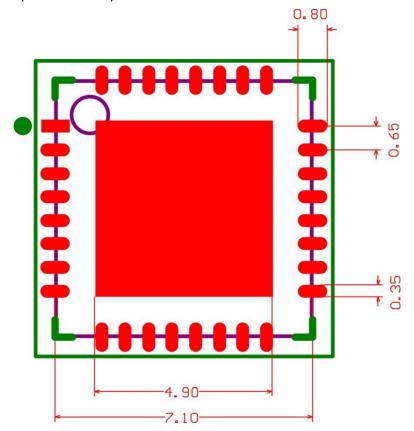


Figure 20.2 32-pin QFN (7mm x 7mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

21 48-pin LQFP

The 48-pin LQFP is used on the following products:

- FT232HL
- FT2232D
- VNC1L-1A
- VNC2-48Q1B

This package is nominally 9.00mm x 9.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

21.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 21.1 48-pin LQFP Scaled Footprint

21.2 Annotated Footprint

The annotated footprint shows key measurements.

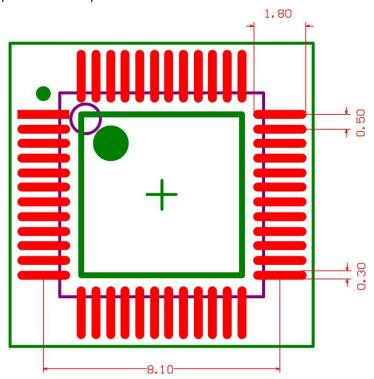


Figure 21.2 48-pin LQFP Annotated Footprint

22 48-pin VQFN/WQFN (7mm x 7mm)

The 48-pin VQFN/WQFN (7mm x 7mm) is used on the following products:

- FT800Q
- FT801Q
- FT810Q
- <u>FT811Q</u>
- <u>FT51AQ</u>

This package is nominally 7.00mm x 7.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

22.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 22.1 48-pin VQFN/WQFN (7mm x 7mm) Scaled Footprint

22.2 Annotated Footprint

The annotated footprint shows key measurements.

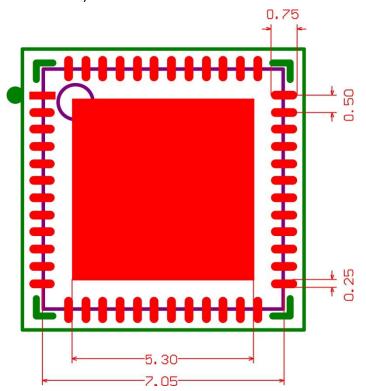


Figure 22.2 48-pin VQFN/WQFN (7mm x 7mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.



48-pin QFN (8mm x 8mm) 23

The 48-pin QFN (8mm x 8mm) is used on the following products:

- VNC2-48Q1B
- FT232HQ

This package is nominally 8.00mm x 8.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

23.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 23.1 48-pin QFN (8mm x 8mm) Scaled Footprint

23.2 Annotated Footprint

The annotated footprint shows key measurements.

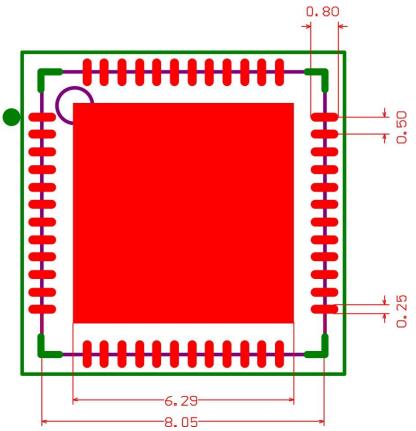


Figure 23.2 48-pin QFN (8mm x 8mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.





24 56-pin QFN (7mm x 7mm)

The 56-pin QFN (7mm x 7mm) is used on the following product:

• <u>FT600Q</u>

This package is nominally 7.00mm x 7.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

24.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 24.1 56-pin QFN (7mm x 7mm) Scaled Footprint

24.2 Annotated Footprint

The annotated footprint shows key measurements.

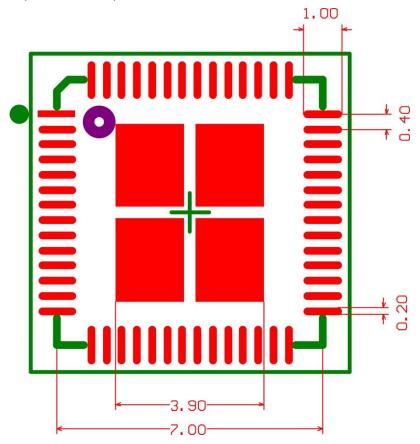


Figure 24.2 56-pin QFN (7mm x 7mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

Note: Connect exposed center pad to GND. Do not place tracks on the top layer of the PCB in this area. Cross-hatching designs used for less solder paste and less heat up rate required.



25 56-pin VQFN (8mm x 8mm)

The 56-pin VQFN (8mm x 8mm) is used on the following products:

- FT812Q
- FT813Q
- FT2232HQ
- FT4232HQ

This package is nominally 8.00mm x 8.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

25.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 25.1 56-pin VQFN (8mm x 8mm) Scaled Footprint

25.2 Annotated Footprint

The annotated footprint shows key measurements.

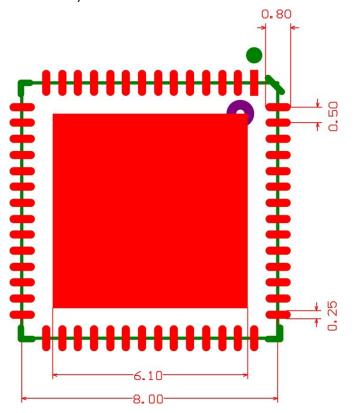


Figure 25.2 56-pin VQFN (8mm x 8mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.



26 64-pin LQFP

The 64-pin LQFP is used on the following products:

- VNC2-64L1B
- FT313HL
- FT2232HL
- FT4232HL

This package is nominally 12.00mm x 12.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

26.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 26.1 64-pin LQFP Scaled Footprint

26.2 Annotated Footprint

The annotated footprint shows key measurements.

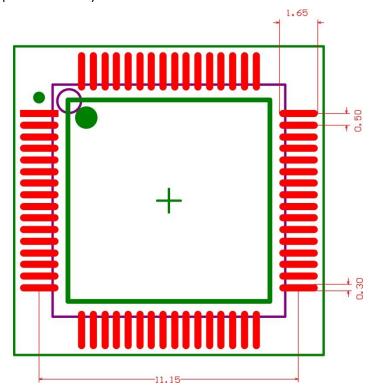


Figure 26.2 64-pin LQFP Annotated Footprint

27 64-pin TQFP

The 64-pin TQFP is used on the following products:

FT313HP

This package is nominally 9.00mm x 9.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

27.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 27.1 64-pin TQFP Scaled Footprint

27.2 Annotated Footprint

The annotated footprint shows key measurements.

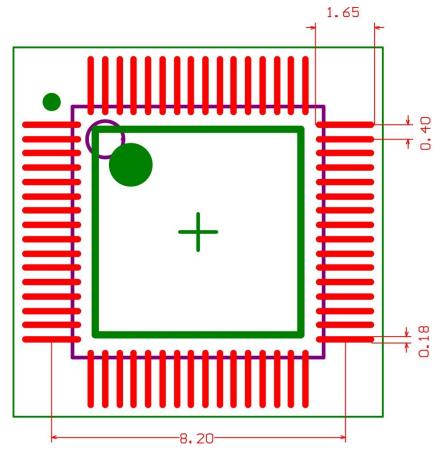


Figure 27.2 64-pin TQFP Annotated Footprint

version 1.

Document Reference No.: FT_001321 Clearance No.: FTDI# 501

28 64-pin QFN (8mm x 8mm)

The 64-pin QFN (8mm x 8mm) is used on the following product:

VNC2-64Q1B

This package is nominally 8.00mm x 8.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

28.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 28.1 64-pin QFN (8mm x 8mm) Scaled Footprint

28.2 Annotated Footprint

The annotated footprint shows key measurements.

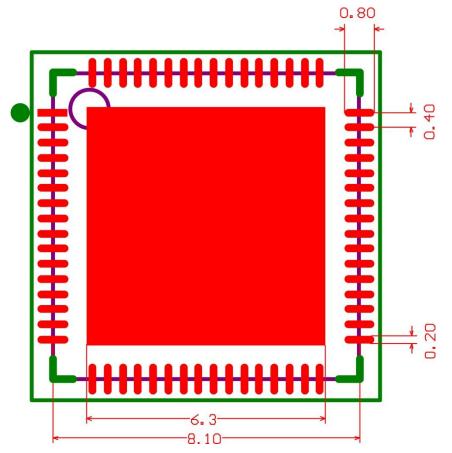


Figure 28.2 64-pin QFN (8mm x 8mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

29 64-pin QFN (9mm x 9mm)

The 64-pin QFN (9mm x 9mm) is used on the following products:

- FT313HO
- FT2232HQ
- FT4232HQ

This package is nominally 9.00mm x 9.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

29.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 29.1 64-pin QFN (9mm x 9mm) Scaled Footprint

29.2 Annotated Footprint

The annotated footprint shows key measurements.

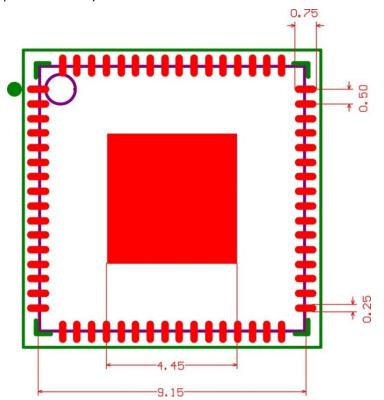


Figure 29.2 64-pin QFN (9mm x 9mm) Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.







29.2.1 **Additional Information**

This package is unique to all the other packages where there is extra strain relief between the exposed pad in the center and the IC pins at the edge of the IC.

The exposed strain relief is connected to the pins so it is very important to ensure that the center exposed pad is not larger than specified, otherwise it could short all the signals together rendering the device and PCB useless.

The exposed strain relief should not be connected to the PCB in any way and this area should be marked as keep out. Only the pins at the edge of the package and the center exposed pad should be connected to the PCB.

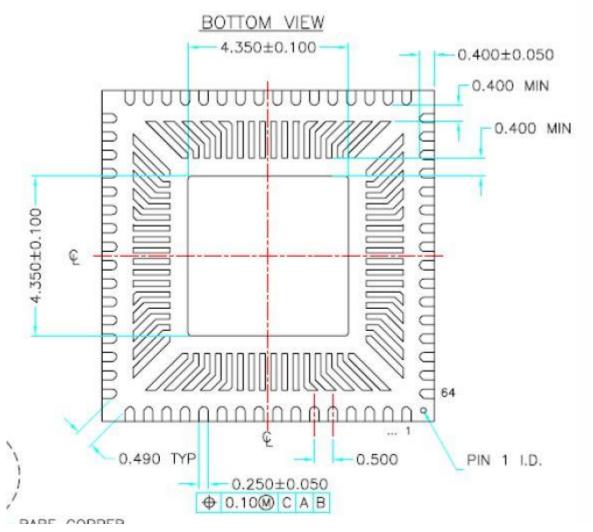


Figure 29.3 64-pin QFN (9mm x 9mm) Bottom View





30 76-pin QFN

The 76-pin QFN is used on the following products:

- FT601Q
- FT9050
- FT906Q
- FT907Q
- <u>FT908Q</u>

This package is nominally 9.00mm x 9.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

30.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 30.1 76-pin QFN Scaled Footprint

30.2 Annotated Footprint

The annotated footprint shows key measurements.

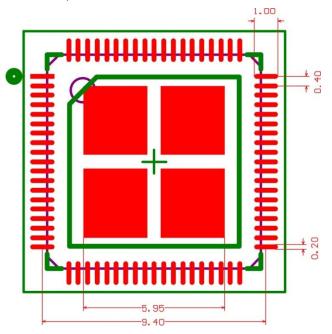


Figure 30.2 76-pin QFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

Note: Connect exposed center pad to GND. Do not place tracks on the top layer of the PCB in this area. Cross-hatching design used for less solders paste and less heat up rate required.





31 80-pin LQFP

The 80-pin LQFP is used on the following products:

- FT905L
- FT906L
- FT907L
- FT908L

This package is nominally 12.00mm x 12.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

31.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 31.1 80-pin LQFP Scaled Footprint

31.2 Annotated Footprint

The annotated footprint shows key measurements.

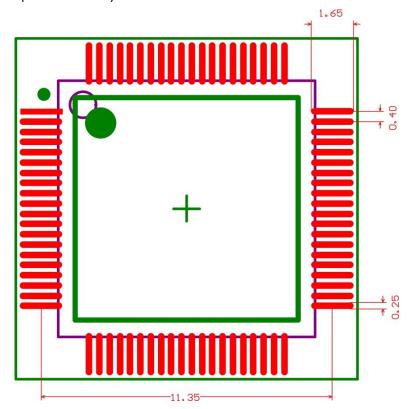


Figure 31.2 80-pin LQFP Annotated Footprint

32 100-pin LQFP

The 100-pin LQFP is used on the following products:

- FT900L
- FT901L
- FT902L
- FT903L

This package is nominally 16.00mm x 16.00mm. The solder pads are on a 0.50mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

32.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 32.1 100-pin LQFP Scaled Footprint

32.2 Annotated Footprint

The annotated footprint shows key measurements.

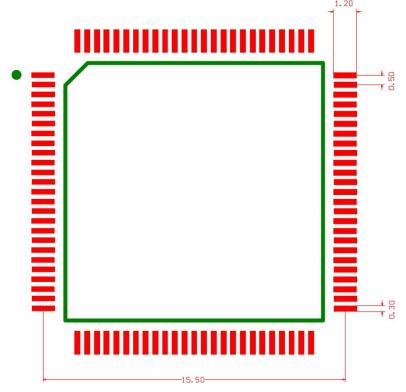


Figure 32.2 100-pin LQFP Annotated Footprint



33 100-pin QFN

The 100-pin QFN is used on the following products:

- FT9000
- FT901Q
- FT9020
- FT903Q

This package is nominally 12.00mm x 12.00mm. The solder pads are on a 0.40mm pitch.

Please see the IC Package Parameters in the IC datasheet for full information.

33.1 Scaled Footprint

This 1:1 scaled footprint is the exact size when viewed or printed at 100%.



Figure 33.1 100-pin QFN Scaled Footprint

33.2 Annotated Footprint

The annotated footprint shows key measurements.

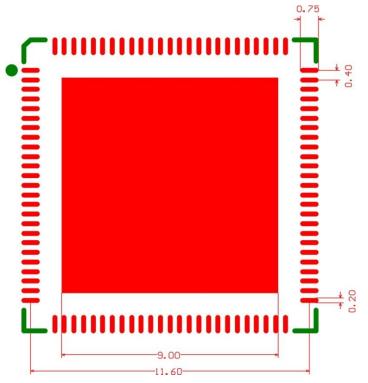


Figure 33.2 100-pin QFN Annotated Footprint

Note: Red = top layer copper, other colors are mechanical layers.

Technical Note **TN_166 FTDI Example IC PCB Footprints**

Document Reference No.: FT_001321 Clearance No.: FTDI# 501

Contact Information 34

Head Office - Glasgow, UK

Future Technology Devices International Limited Unit 1, 2 Seaward Place, Centurion Business Park Glasgow G41 1HH

United Kingdom

Tel: +44 (0) 141 429 2777 Fax: +44 (0) 141 429 2758

E-mail (Sales) sales1@ftdichip.com E-mail (Support) support1@ftdichip.com E-mail (General Enquiries) admin1@ftdichip.com

Branch Office - Taipei, Taiwan

Future Technology Devices International Limited

(Taiwan)

2F, No. 516, Sec. 1, NeiHu Road

Taipei 114

Taiwan, R.O.C. Tel: +886 (0) 2 8797 1330

Fax: +886 (0) 2 8751 9737

E-mail (Sales) tw.sales1@ftdichip.com E-mail (Support) tw.support1@ftdichip.com E-mail (General Enquiries) tw.admin1@ftdichip.com

Branch Office - Tigard, Oregon, USA

Future Technology Devices International Limited

(USA)

7130 SW Fir Loop Tigard, OR 97223-8160

USA

Tel: +1 (503) 547 0988

Fax: +1 (503) 547 0987

E-Mail (Sales) us.sales@ftdichip.com E-Mail (Support) us.support@ftdichip.com E-Mail (General Enquiries) us.admin@ftdichip.com

Branch Office - Shanghai, China

Future Technology Devices International Limited

(China)

Room 1103, No. 666 West Huaihai Road,

Shanghai, 200052

China

Tel: +86 21 62351596 Fax: +86 21 62351595

E-mail (Sales) cn.sales@ftdichip.com E-mail (Support) cn.support@ftdichip.com E-mail (General Enquiries) cn.admin@ftdichip.com

Web Site

http://ftdichip.com

Distributor and Sales Representatives

Please visit the Sales Network page of the FTDI Web site for the contact details of our distributor(s) and sales representative(s) in your country.

System and equipment manufacturers and designers are responsible to ensure that their systems, and any Future Technology Devices International Ltd (FTDI) devices incorporated in their systems, meet all applicable safety, regulatory and system-level performance requirements. All application-related information in this document (including application descriptions, suggested FTDI devices and other materials) is provided for reference only. While FTDI has taken care to assure it is accurate, this information is subject to customer confirmation, and FTDI disclaims all liability for system designs and for any applications assistance provided by FTDI. Use of FTDI devices in life support and/or safety applications is entirely at the user's risk, and the user agrees to defend, indemnify and hold harmless FTDI from any and all damages, claims, suits or expense resulting from such use. This document is subject to change without notice. No freedom to use patents or other intellectual property rights is implied by the publication of this document. Neither the whole nor any part of the information contained in, or the product described in this document, may be adapted or reproduced in any material or electronic form without the prior written consent of the copyright holder. Future Technology Devices International Ltd, Unit 1, 2 Seaward Place, Centurion Business Park, Glasgow G41 1HH, United Kingdom. Scotland Registered Company Number: SC136640



Version 1.1

Document Reference No.: FT_001321 Clearance No.: FTDI# 501



Appendix A - References

Document References

http://www.ftdichip.com/Support/Documents/PCBData.htm http://www.ftdichip.com/Products/ICs.htm

Acronyms and Abbreviations

Terms	Description
DFN	Dual-Flat No-Leads Package
IC	Integrated Circuit
LQFP	Low Profile Quad Flat Package
PCB	Printed Circuit Board
QFN	Quad Flat No-Leads Package
SSOP	Shrink Small-Outline Package
TSSOP	Thin-Shrink Small Outline Package
VQFN / WQFN	Very Thin Quad Flat No-Lead Package





Appendix B – List of Tables & Figures

List of Tables

Table 1.1 Unavailable Footprints	6
Table 3.1 DFN Packages	8
Table 3.2 QFP Packages	8
Table 3.3 QFN Packages	9
Table 3.4 SSOP Packages	9
List of Figures	
Figure 2.1 DFN Packages	7
Figure 2.2 QFP Packages	7
Figure 2.3 QFN Packages	7
Figure 2.4 SSOP Packages	7
Figure 4.1 10-pin DFN Scaled Footprint	10
Figure 4.2 10-pin DFN Annotated Footprint	10
Figure 5.1 12-pin DFN Scaled Footprint	11
Figure 5.2 12-pin DFN Annotated Footprint	11
Figure 6.1 16-pin QFN (3mm x 3mm) Scaled Footprint	12
Figure 6.2 16-pin QFN (3mm x 3mm) Annotated Footprint	12
Figure 7.1 16-pin QFN (4mm x 4mm) Scaled Footprint	13
Figure 7.2 16-pin QFN (4mm x 4mm) Annotated Footprint	13
Figure 8.1 16-pin SSOP Scaled Footprint	14
Figure 8.2 16-pin SSOP Annotated Footprint	14
Figure 9.1 16-pin TSSOP Scaled Footprint	15
Figure 9.2 16-pin TSSOP Annotated Footprint	15
Figure 10.1 20-pin QFN Scaled Footprint	16
Figure 10.2 20-pin QFN Annotated Footprint	16
Figure 11.1 20-pin SSOP Scaled Footprint	17
Figure 11.2 20-pin SSOP Annotated Footprint	17
Figure 12.1 24-pin QFN Scaled Footprint	18
Figure 12.2 24-pin QFN Annotated Footprint	18
Figure 13.1 24-pin SSOP Scaled Footprint	19
Figure 13.2 24-pin SSOP Annotated Footprint	19
Figure 14.1 28-pin QFN Scaled Footprint	20
Figure 14.2 28-pin QFN Annotated Footprint	20
Figure 15.1 28-pin SSOP Scaled Footprint	21



TN_166 FTDI Example IC PCB Footprints



Document Reference No.: FT_001321 Clearance No.: FTDI# 501



Figure 15.2 28-pin SSOP Annotated Footprint	21
Figure 16.1 28-pin TSSOP Scaled Footprint	22
Figure 16.2 28-pin TSSOP Annotated Footprint	22
Figure 17.1 28-pin WQFN Scaled Footprint	23
Figure 17.2 28-pin WQFN Annotated Footprint	. 23
Figure 18.1 32-pin LQFP Scaled Footprint	. 24
Figure 18.2 32-pin LQFP Annotated Footprint	. 24
Figure 19.1 32-pin VQFN/QFN (5mm x 5mm) Scaled Footprint	. 25
Figure 19.2 32-pin VQFN/QFN (5mm x 5mm) Annotated Footprint	. 25
Figure 20.1 32-pin QFN (7mm x 7mm) Scaled Footprint	. 26
Figure 20.2 32-pin QFN (7mm x 7mm) Annotated Footprint	26
Figure 21.1 48-pin LQFP Scaled Footprint	. 27
Figure 21.2 48-pin LQFP Annotated Footprint	. 27
Figure 22.1 48-pin VQFN/WQFN (7mm x 7mm) Scaled Footprint	28
Figure 22.2 48-pin VQFN/WQFN (7mm x 7mm) Annotated Footprint	
Figure 23.1 48-pin QFN (8mm x 8mm) Scaled Footprint	29
Figure 23.2 48-pin QFN (8mm x 8mm) Annotated Footprint	29
Figure 24.1 56-pin QFN (7mm x 7mm) Scaled Footprint	30
Figure 24.2 56-pin QFN (7mm x 7mm) Annotated Footprint	30
Figure 25.1 56-pin VQFN (8mm x 8mm) Scaled Footprint	31
Figure 25.2 56-pin VQFN (8mm x 8mm) Annotated Footprint	31
Figure 26.1 64-pin LQFP Scaled Footprint	32
Figure 26.2 64-pin LQFP Annotated Footprint	32
Figure 27.1 64-pin TQFP Scaled Footprint	33
Figure 27.2 64-pin TQFP Annotated Footprint	33
Figure 28.1 64-pin QFN (8mm x 8mm) Scaled Footprint	34
Figure 28.2 64-pin QFN (8mm x 8mm) Annotated Footprint	34
Figure 29.1 64-pin QFN (9mm x 9mm) Scaled Footprint	35
Figure 29.2 64-pin QFN (9mm x 9mm) Annotated Footprint	35
Figure 29.3 64-pin QFN (9mm x 9mm) Bottom View	36
Figure 30.1 76-pin QFN Scaled Footprint	37
Figure 30.2 76-pin QFN Annotated Footprint	37
Figure 31.1 80-pin LQFP Scaled Footprint	38
Figure 31.2 80-pin LQFP Annotated Footprint	38
Figure 32.1 100-pin LQFP Scaled Footprint	39
Figure 32.2 100-pin LQFP Annotated Footprint	39
Figure 33.1 100-pin QFN Scaled Footprint	40
Figure 33.2 100-pin QFN Annotated Footprint	40



Technical Note TN_166 FTDI Example IC PCB Footprints

Version 1.1

Document Reference No.: FT_001321 Clearance No.: FTDI# 501

Appendix C - Revision History

Document Title: TN_166 FTDI Example IC PCB Footprints

Document Reference No.: FT_001321
Clearance No.: FTDI# 501

Product Page: http://www.ftdichip.com/FTProducts.htm

Document Feedback: Send Feedback

Revision	Changes	Date
1.0	Initial Release	2016-04-27
1.1	Updated Release	2017-05-16